# INTERNATIONAL STANDARD

### IEC 60747-4-1

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#### Semiconductor devices – Discrete devices –

#### Part 4-1:

Microwave diodes and transistors – Microwave field effect transistors – Blank detail specification

Dispositifs à semiconducteurs - Dispositifs discrets -

#### Partie 4-1:

Diodes et transistors hyperfréquences – Transistors hyperfréquences à effet de champ – Spécification particulière-cadre

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Commission Electrotechnique Internationale International Electrotechnical Commission Международная Электротехническая Комиссия

PRICE CODE



#### INTERNATIONAL ELECTROTECHNICAL COMMISSION

#### SEMICONDUCTOR DEVICES - DISCRETE DEVICES -

## Part 4-1: Microwave diodes and transistors – Microwave field effect transistors – Blank detail specification

#### **FOREWORD**

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International Standard IEC 60747-4-1 has been prepared by subcommittee 47E: Discrete semiconductor devices, of IEC technical committee 47: Semiconductor devices.

The text of this standard is based on the following documents:

FDIS	Report on voting
47E/145/FDIS	47E/154/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 3.

Annex A forms an integral part of this standard.

The QC number that appears on the front cover of this publication is the specification number in the IEC Quality Assessment System for Electronic Components (IECQ).

Other IEC publications quoted in this standard:

Publication Nos.

IEC 60191-2:1966, Mechanical standardization of semiconductor devices – Part 2: Dimensions

IEC 60747-8-1:1987, Semiconductor devices – Discrete devices – Part 8: Field-effect transistors – Section One: Blank detail specification for single-gate field-effect transistors up to 5 W and 1 GHz

IEC 60747-10:1991, Semiconductor devices – Part 10: Generic specification for discrete devices and integrated circuits

IEC 70747-11:1985, Semiconductor devices – Part 11: Sectional specification for discrete devices

IEC 60749:1996, Semiconductor devices – Mechanical and climatic test methods

The committee has decided that the contents of this publication will remain unchanged until 2005. At this date, the publication will be

- reconfirmed;
- withdrawn;
- · replaced by a revised edition, or
- amended.

A bilingual version of this standard may be issued at a later date.

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#### INTRODUCTION

The IEC Quality Assessment for Electronic Components is operated in accordance with the statutes of the IEC and under the authority of the IEC. The object of this system is to define quality assessment procedures in such a manner that electronic components released by one participating country as conforming with the requirements of an applicable specification are equally acceptable in all other participating countries without the need for further testing.

This blank detail specification is one of a series of blank detail specifications for semiconductor devices and shall be used with the following IEC publications:

- 60747-10/QC 700000: Semiconductor devices Part 10: Generic specification for discrete devices and integrated circuits.
- 60747-11/QC 750100: Semiconductor devices Part 11: Sectional specification for discrete devices.